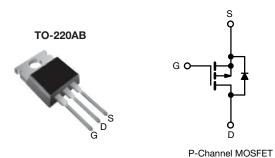


## **Power MOSFET**



PRODUCT SUMMARY					
V <sub>DS</sub> (V)	-10	-100			
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = -10 V	0.60			
Q <sub>g</sub> max. (nC)	18	18			
Q <sub>gs</sub> (nC)	3.	3.0			
Q <sub>gd</sub> (nC)	9.	9.0			
Configuration	Sing	Single			

#### **FEATURES**

- Dynamic dv/dt rating
- · Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

#### **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF9520PbF
Lead (Pb)-free and halogen-free	IRF9520PbF-BE3

ABSOLUTE MAXIMUM RATINGS ( $T_C$	= 25 °C, unle	ess otherwis	e noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	-100	V	
Gate-source voltage			V <sub>GS</sub>	± 20		
Continuous drain current	V <sub>GS</sub> at 10 V	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$		-6.8	А	
		T <sub>C</sub> = 100 °C	I <sub>D</sub>	-4.8		
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	-27		
Linear derating factor				0.40	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	300	mJ	
Repetitive avalanche current a			I <sub>AR</sub>	-6.8	А	
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	6.0	mJ	
Maximum power dissipation	T <sub>C</sub> =	25 °C	P <sub>D</sub>	60	W	
Peak diode recovery dV/dt <sup>c</sup>			dv/dt	-5.5	V/ns	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering recommendations (peak temperature) <sup>d</sup>	For 10 s			300		
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b.  $V_{DD}$  = -25 V, starting  $T_J$  = 25 °C, L = 9.7 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = -6.8 A (see fig. 12)
- c.  $I_{SD} \le -6.8 \text{ A}$ ,  $di/dt \le 110 \text{ A/}\mu\text{s}$ ,  $V_{DD} \le V_{DS}$ ,  $T_J \le 175 \text{ °C}$
- d. 1.6 mm from case



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62		
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50	-	°C/W	
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	2.5		

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0$	-100	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I <sub>D</sub> = -1 mA	ī	-0.10	-	V/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = \	/ <sub>GS</sub> , I <sub>D</sub> = -250 μA	-2.0	-	-4.0	V
Gate-source leakage	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
7		V <sub>DS</sub> = -100 V, V <sub>GS</sub> = 0 V		-	-	-100	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = -80 \text{ V},$	V <sub>DS</sub> = -80 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C		-	-500	
Drain-source on-state resistance	R <sub>DS(on)</sub>		I <sub>D</sub> = -4.1 A <sup>b</sup>	-	-	0.60	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = -5	50 V, I <sub>D</sub> = -4.1 A <sup>b</sup>	2.0	-	-	S
Dynamic		•			•	•	
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = -25 \text{ V},$ $f = 1.0 \text{ MHz, see fig. 5}$		=.	390	-	
Output capacitance	C <sub>oss</sub>			-	170	-	pF
Reverse transfer capacitance	C <sub>rss</sub>			-	45	-	1
Total gate charge	Qg	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -6.8 A, V <sub>DS</sub> = -80 V, see fig. 6 and 13 <sup>b</sup>	-	-	18	nC
Gate-source charge	Q <sub>gs</sub>			-	-	3.0	
Gate-drain charge	$Q_{gd}$			-	-	9.0	
Turn-on delay time	t <sub>d(on)</sub>			-	9.6	-	
Rise time	t <sub>r</sub>	V <sub>DD</sub> = -	$V_{DD} = -50 \text{ V}, I_D = -6.8 \text{ A},$		29	-	ns
Turn-off delay time	t <sub>d(off)</sub>	$R_g$ = 18 $\Omega$ , $R_D$ = 7.1 $\Omega$ , see fig. 10 $^b$		-	21	-	
Fall time	t <sub>f</sub>			-	25	-	
Gate input resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.8	-	3.9	Ω
Internal drain inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	ъЦ
Internal source inductance	L <sub>S</sub>			-	7.5	-	- nH
<b>Drain-Source Body Diode Characteristic</b>	cs						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	-6.8	- A
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>			-	-	-27	_ ^
Body diode voltage	$V_{SD}$	$T_J = 25  ^{\circ}\text{C},  I_S = -6.8  \text{A},  V_{GS} = 0  \text{V}^{ \text{b}}$		=.	-	-6.3	V
Body diode reverse recovery time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = -6.8 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s b}$		-	98	200	ns
Body diode reverse recovery charge	Q <sub>rr</sub>			-	0.33	0.66	μC
Forward turn-on time	t <sub>on</sub>	Intrinsic turi	n-on time is negligible (turn	on is do	minated b	y L <sub>S</sub> and	L <sub>D</sub> )

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq$  300 µs; duty cycle  $\leq$  2 %



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

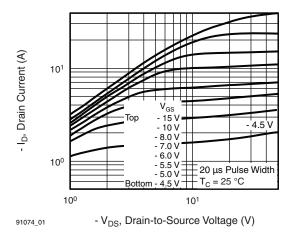


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

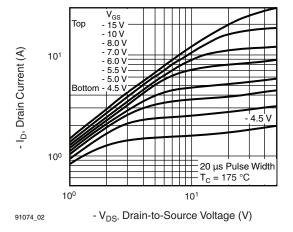


Fig. 2 - Typical Output Characteristics,  $T_C = 175$  °C

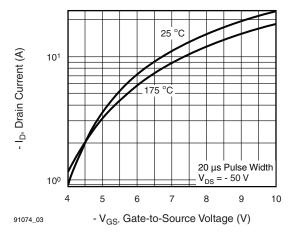


Fig. 3 - Typical Transfer Characteristics

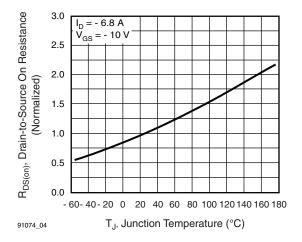


Fig. 4 - Normalized On-Resistance vs. Temperature

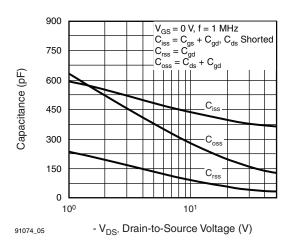


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

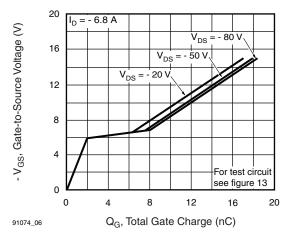


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



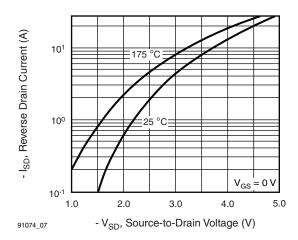


Fig. 7 - Typical Source-Drain Diode Forward Voltage

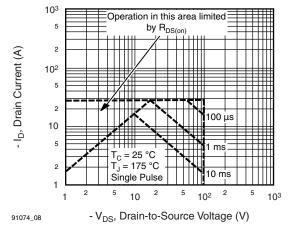


Fig. 8 - Maximum Safe Operating Area

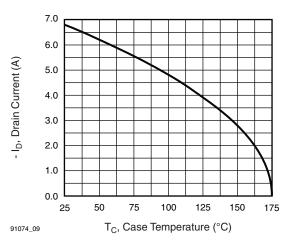


Fig. 9 - Maximum Drain Current vs. Case Temperature

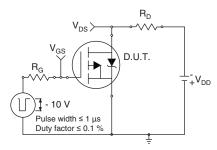


Fig. 10a - Switching Time Test Circuit

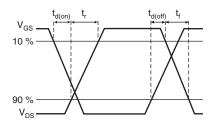


Fig. 10b - Switching Time Waveforms

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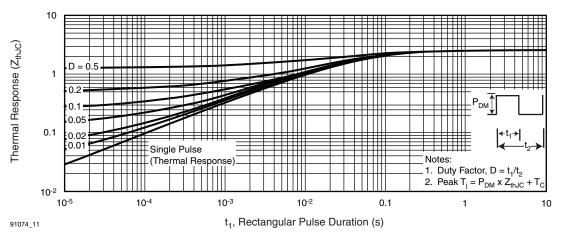


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



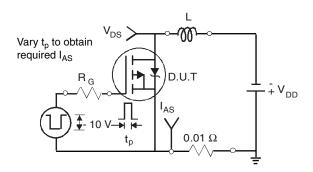


Fig. 12a - Unclamped Inductive Test Circuit

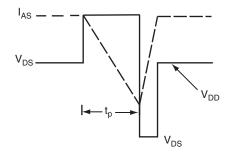


Fig. 12b - Unclamped Inductive Waveforms

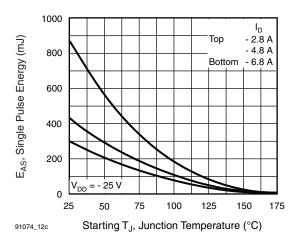


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

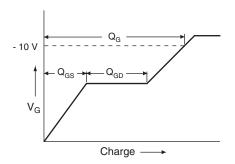


Fig. 13a - Basic Gate Charge Waveform

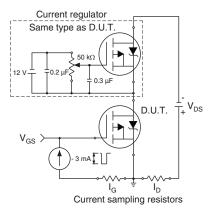
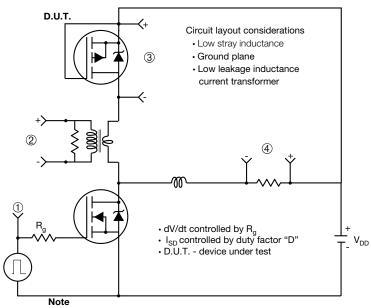


Fig. 13b - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



• Compliment N-Channel of D.U.T. for driver

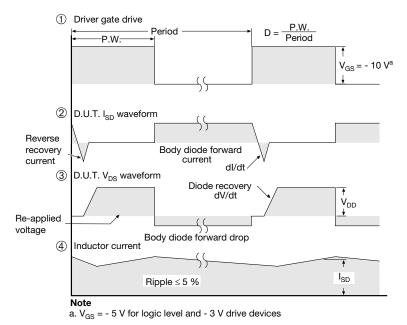


Fig. 14 - For P-Channel

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